PCN Number:	20181210001	**PCN Date:**	12/18/2018
Title:	DLP Controller (ASIC) BUMP Site change		
Customer Contact:	Dlp-pcn-team@list.ti.com	**Dept:**	DLP CQE
Proposed 1st Ship Date:	no earlier than 04/01/2019	**Estimated Sample Availability:**	12/18/2018

Change Type:

☐	Assembly Site	☐	Design	☒	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☒	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☒	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

An alternate BUMP/RDL site has been qualified for the devices listed in 'Product Affected' section below.

	Current Location	New Location
BUMP/RDL Location	Sony, Oita	Amkor K5, South Korea

Amkor's standard material and process will be applied for new Bump/RDL products with bump material changing from Sn/Cu to Sn/Ag.

Material from new site is expected to ship no earlier than April 1st, 2019. After April 1st, 2019, customers may receive devices from either location.

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

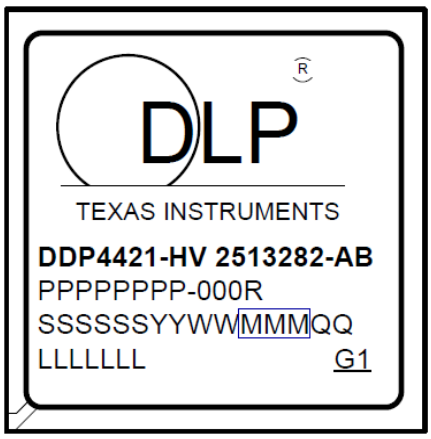
None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.

Changes to product identification resulting from this PCN:

Manufacturing site code on the device marking will be updated to distinguish material from two locations



MMM: Manufacturing Site

Example manufacturing site code changes:

Device	Current Marking	New Marking
DDP442x (ASE Assembly)	H**A**L	H**C**L
DDP442x (J-Devices Assembly)	H**B**L	H**D**L
DDP442x-HV	H**A**L	H**B**L

Product Affected:

Device	Orderable P/N
DDP4421	2511897-0001
DDP4422	2511898-0001
DDP4421-HV	2513282-0001
DDP4422-HV	2513283-0001
DDP5423	2512621-0001
DLPC900	DLPC900ZPC
DLPC6421	DLPC6421ZPC

Qualification Data

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle: DDP4421 (ASE Assembly), DDP4421(J-Devices Assembly) and DDP4421-HV

Qualification: ☐ **Plan** ☒ **Test Results**

Test	Conditions	Sample Size	Results
Precondition	30℃/70% RH/216hrs, 255℃ max (4 times)	96pcs	Pass
TCT	-55℃/125℃; 1000cycles	32pcs	Pass
uHAST	110℃/85% RH; 500hrs	32pcs	Pass
THB	85℃/85% RH, Vdd max; 1000hrs	32pcs	Pass
HTS	150℃; 1000hrs	32pcs	Pass

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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